



Material Content Data Sheet



Sales Product Name		BAS 52-02V H6327		Issued		29. August 2013		
MA#		MA000770608						
Package		PG-SC79-2-1		Weight*		1.68 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		46	
	noble metal	gold	7440-57-5	0.008	0.46		4595	
	inorganic material	silicon	7440-21-3	0.044	2.62	3.08	26165	30807
leadframe	inorganic material	silicon	7440-21-3	0.000	0.01		92	
	non noble metal	titanium	7440-32-6	0.001	0.05		458	
	non noble metal	chromium	7440-47-3	0.002	0.14		1373	
	non noble metal	copper	7440-50-8	0.767	45.59	45.79	455880	457800
wire	non noble metal	copper	7440-50-8	0.007	0.40	0.40	4024	4024
encapsulation	organic material	carbon black	1333-86-4	0.007	0.42		4225	
	plastics	epoxy resin	-	0.121	7.18		71823	
	inorganic material	silicondioxide	60676-86-0	0.583	34.64	42.24	346440	422489
leadfinish	non noble metal	tin	7440-31-5	0.055	3.24	3.24	32427	32427
plating	noble metal	silver	7440-22-4	0.088	5.25	5.25	52452	52452
*deviation	< 10%		Sum in total:			100,00		1000000

Important Remarks:

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